

**SURFACE MOUNT POWER SUPPLIES
FOR STANDARD ASSEMBLY PROCESS**

ABSTRACT

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This improved surface mount power supply can withstand the rigors of the manufacturing process and still create sturdy and robust connection to a user's circuit card. The open frame power module uses a U-shaped or T-shaped interconnect rather than a spherical interconnect. In one embodiment, the U-shaped interconnect can have a
10 hole through one surface to allow the wicking of solder. The wicked solder provides a sturdier connection that is more likely to survive subsequent reflow processes. The power module is also built on a thicker FR4 board. The thicker board is less likely to warp during subsequent heating.

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